



US00D674761S

(12) **United States Design Patent**  
**Iida et al.**

(10) **Patent No.:** **US D674,761 S**

(45) **Date of Patent:** **\*\* Jan. 22, 2013**

(54) **WAFER HOLDING MEMBER**

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(73) Assignee: **Tokyo Electron Limited**, Minato-Ku (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/414,719**

(22) Filed: **Mar. 2, 2012**

(30) **Foreign Application Priority Data**

Oct. 20, 2011 (JP) ..... 2011-024074

(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
118/500, 725, 728, 729; 294/103.1; 414/217,  
414/222.01, 416.03, 941

See application file for complete search history.

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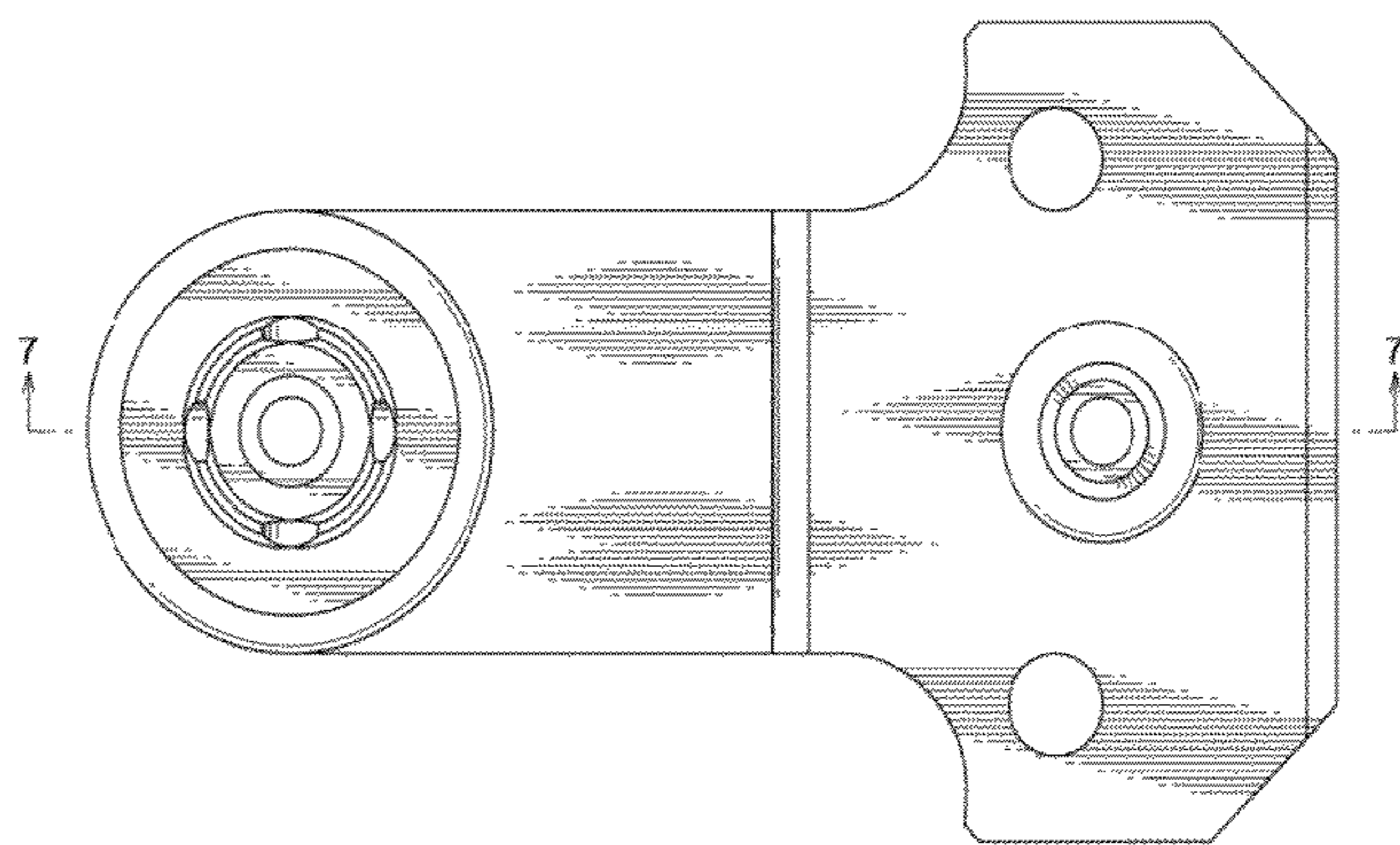
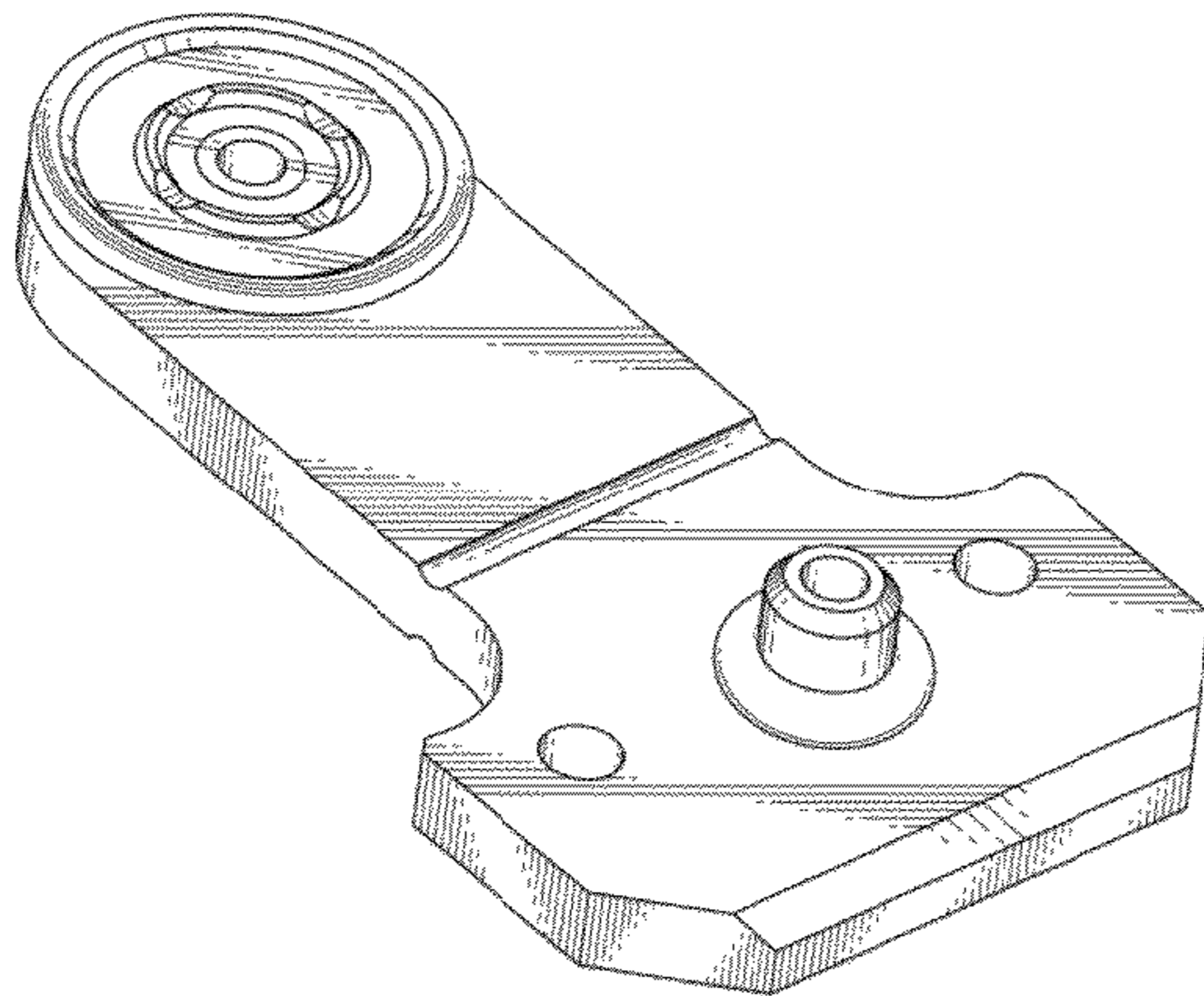
(57) **CLAIM**

The ornamental design for wafer holding member, as shown and described.

**DESCRIPTION**

FIG. 1 is front perspective view of a wafer holding member illustrating our new design;  
 FIG. 2 is a top plan view thereof;  
 FIG. 3 is a bottom view thereof;  
 FIG. 4 is a front view thereof, the rear view being a mirror image;  
 FIG. 5 is a left side view thereof;  
 FIG. 6 is a right side view thereof;  
 FIG. 7 is a sectional view taken along line 7-7 of FIG. 2;  
 FIG. 8 is an enlarged view of portion 8 encircled in FIG. 7; and,  
 FIG. 9 is a perspective view of wafer holding members in use. The broken lines are shown for illustrative purposes only and form no part of the claimed design.

**1 Claim, 8 Drawing Sheets**



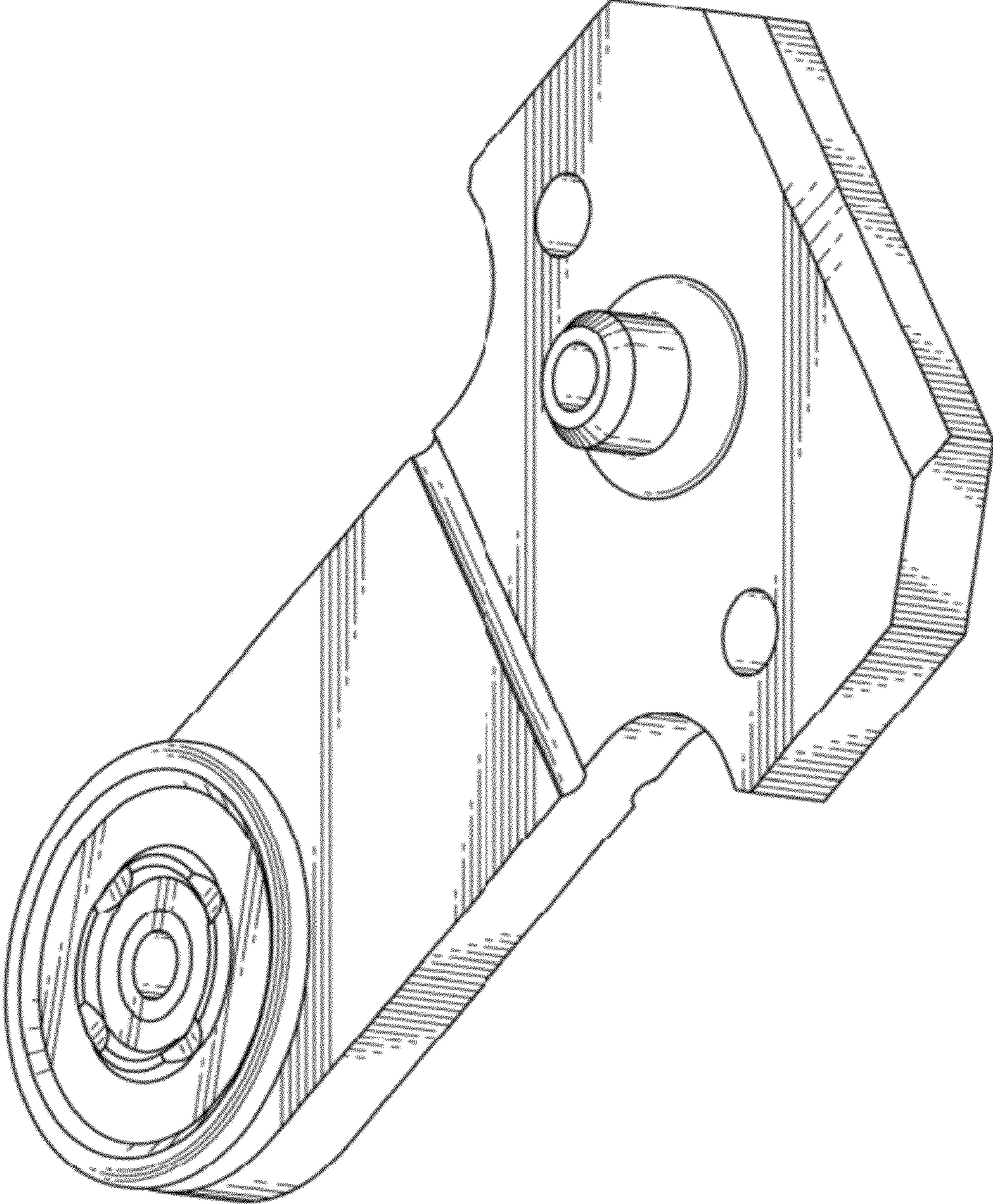


FIG. 1

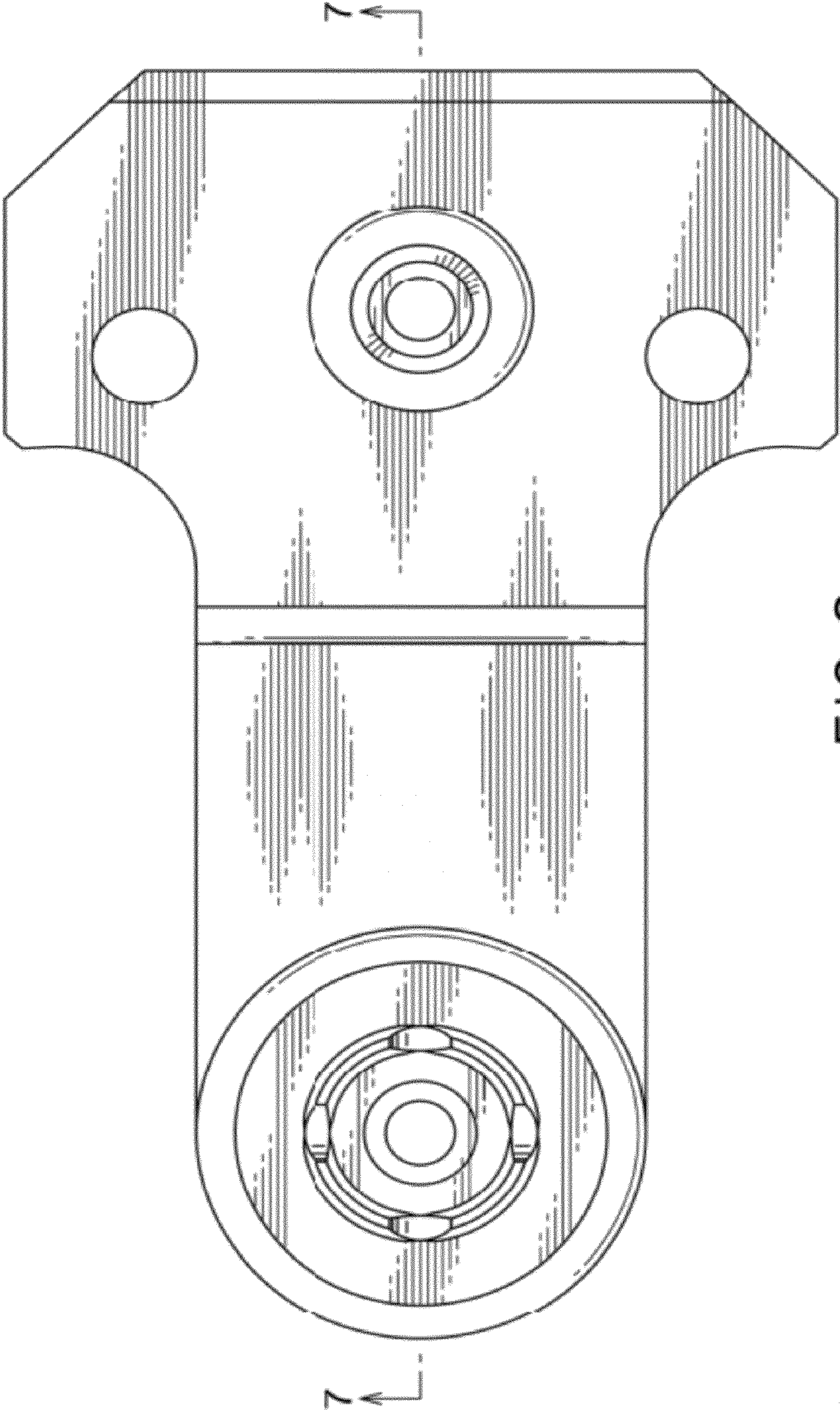


FIG. 2

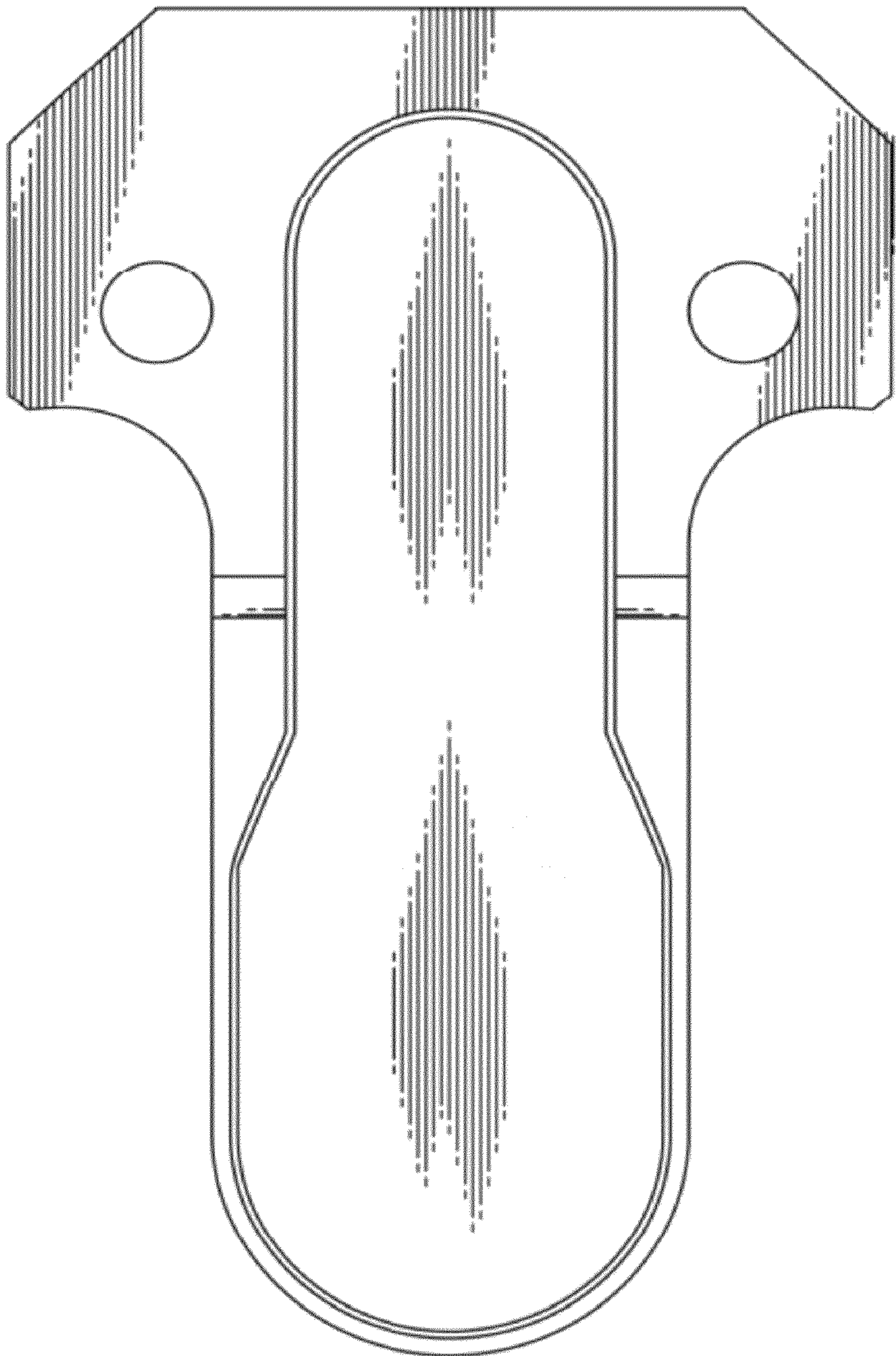


FIG. 3

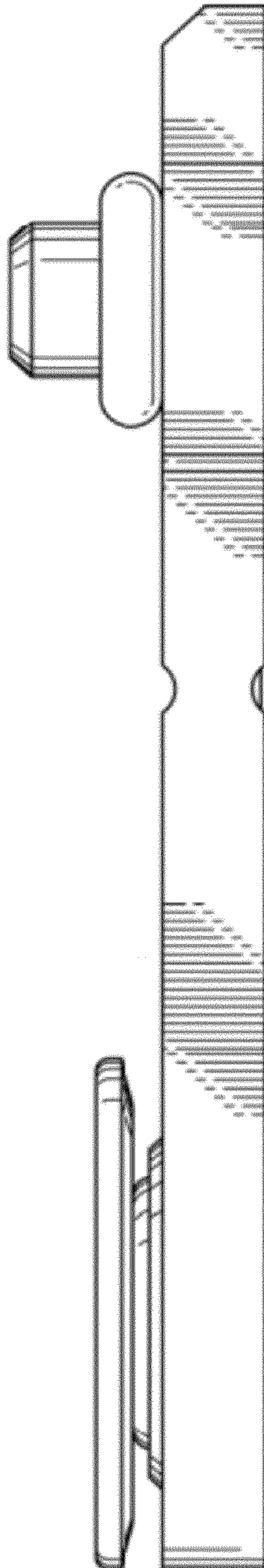


FIG. 4

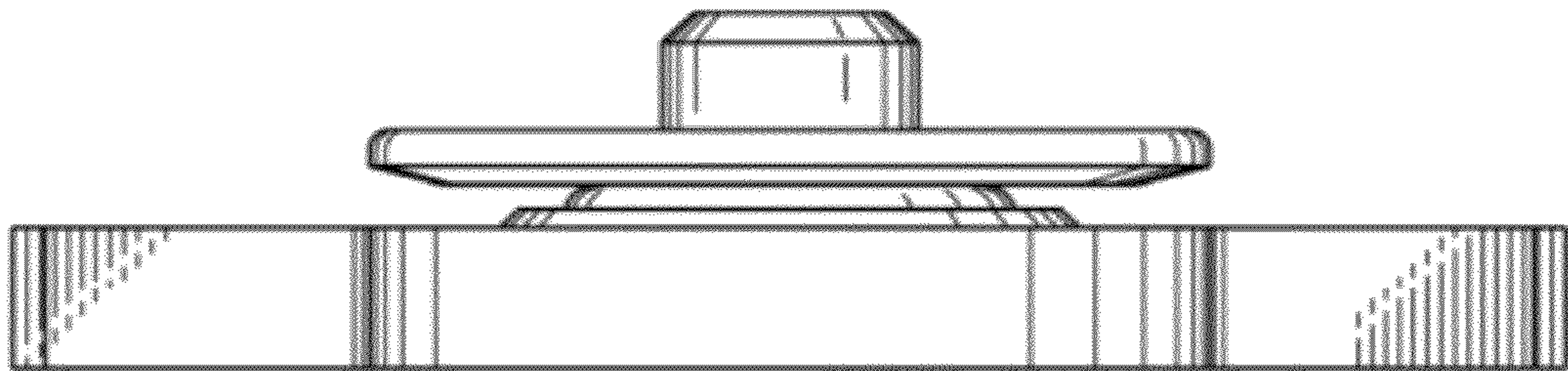


FIG. 5

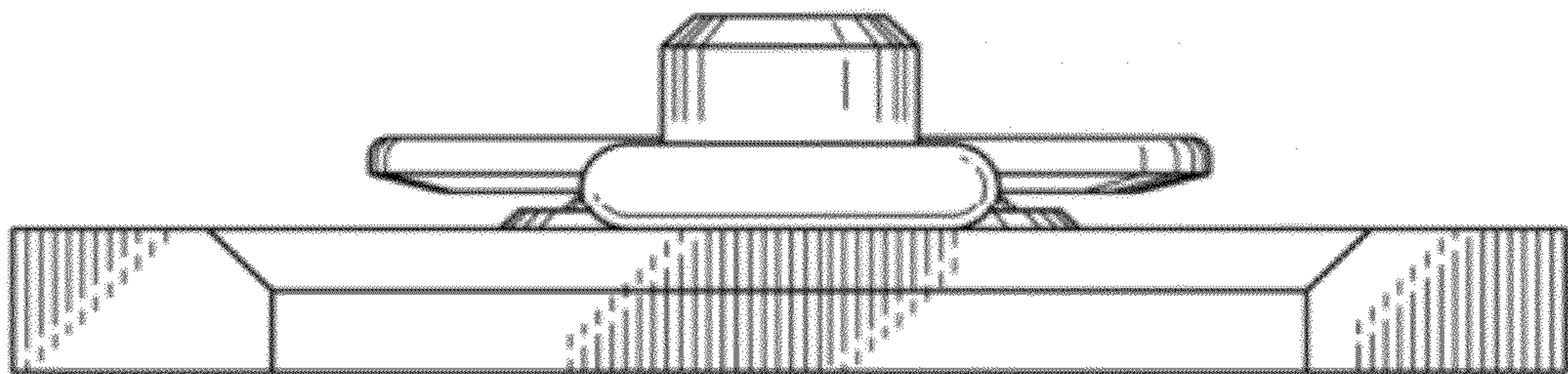


FIG. 6

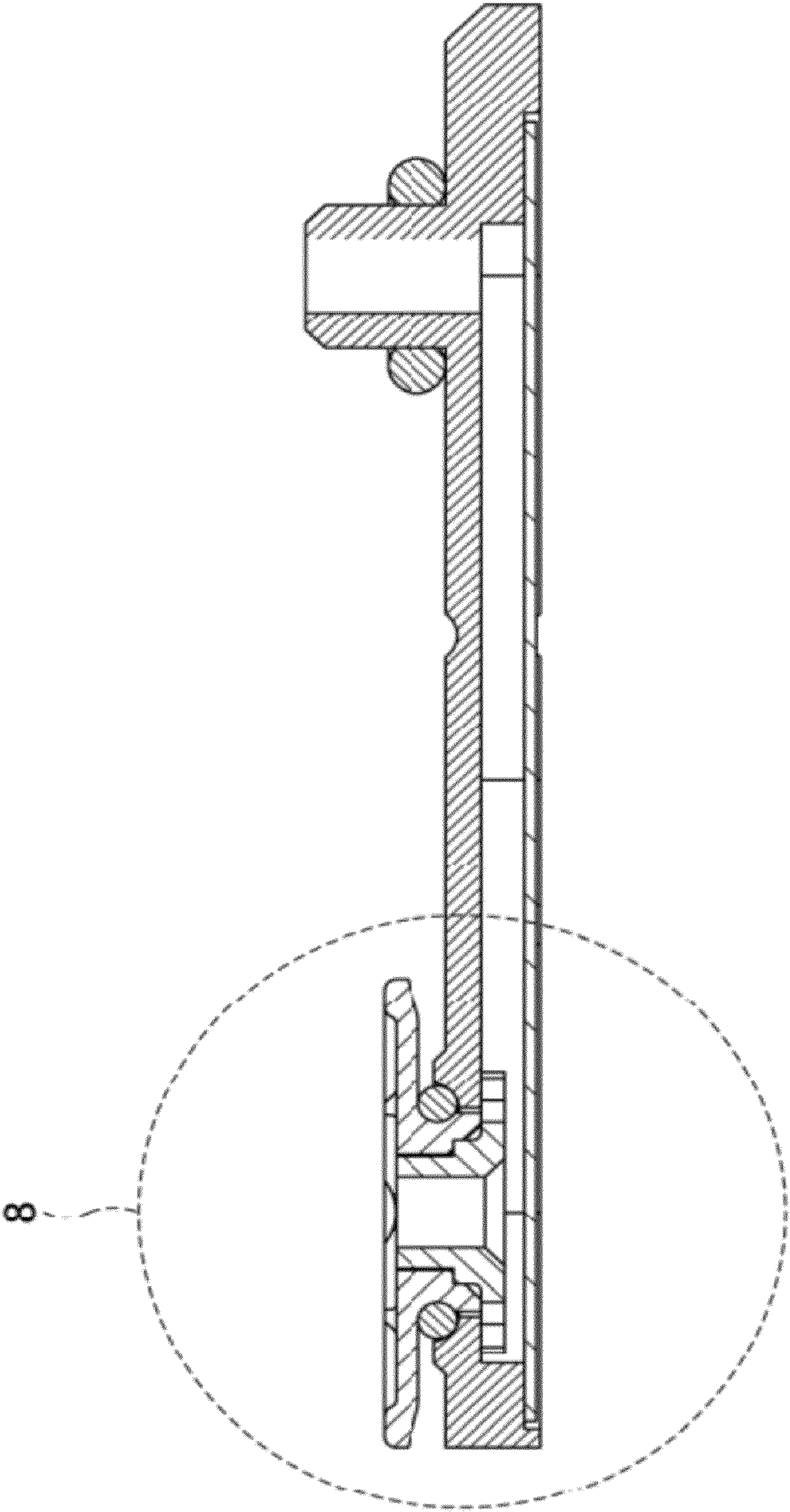


FIG. 7

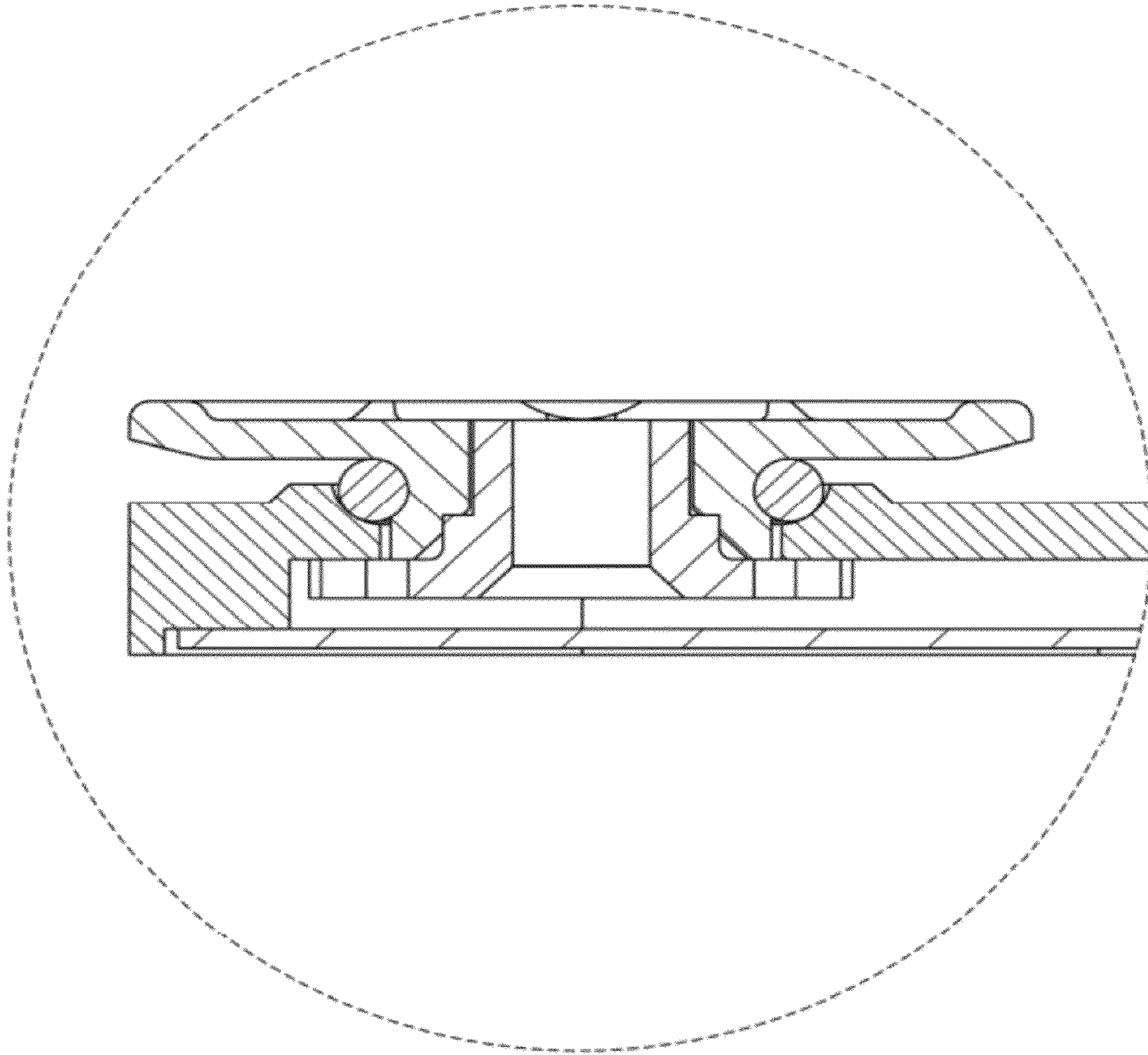


FIG. 8



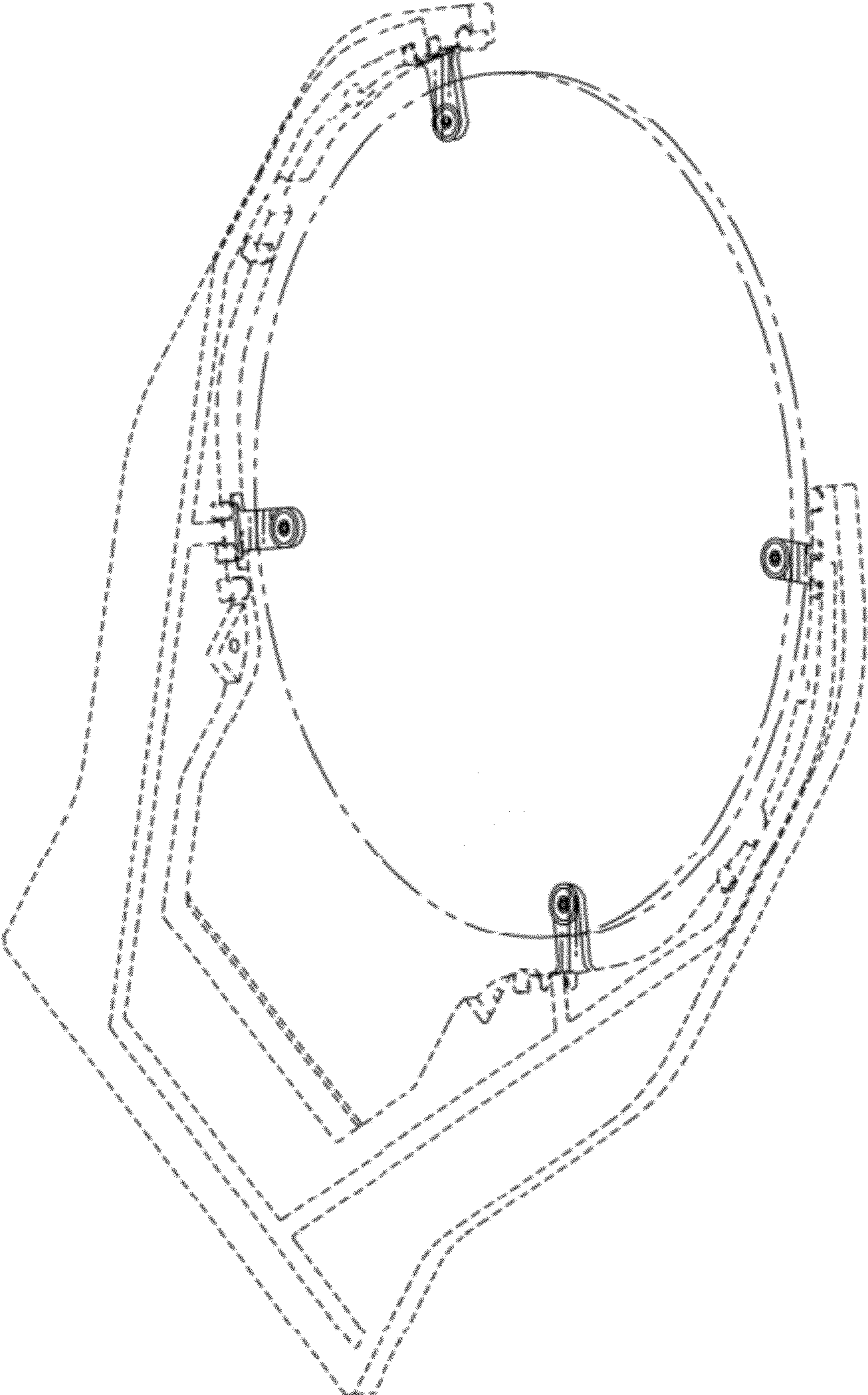


FIG. 9